

USPTO Serial No. 93,671 (Docket No. ISOT-020)

Amendments to the Claims: (strikethrough parts deleted and underlined parts added)**Please delete Claims 14-15, 18-22 without prejudice.**

1. (Currently Amended) A thermal management socket system, comprising:
a thermal management unit having a chamber, wherein said chamber is to receive ~~capable~~
~~of receiving~~ at least one electronic device and wherein said thermal management unit is to
directly apply liquid coolant to said at least one electronic device within said chamber;
a plurality of first connectors within said chamber of said thermal management unit,
wherein said first connectors are adapted for electrically coupling ~~may be electrically coupled~~
with a corresponding plurality of device connectors of said at least one electronic device; and
a plurality of second connectors extending out from said thermal management unit,
wherein said second connectors are electrically coupled to said first connectors and wherein said
second connectors are adapted for ~~may be~~ removably and electrically coupled coupling to a
socket on a board.

2. (Previously Amended) The thermal management socket system of Claim 1, including
a liquid thermal management system coupled to said chamber for thermally managing said at
least one electronic device.

3. (Original) The thermal management socket system of Claim 2, wherein said liquid
thermal management system is comprised of spray cooling.

4. (Original) The thermal management socket system of Claim 2, wherein said liquid
thermal management system is comprised of liquid immersion.

5. (Previously Canceled)

6. (Previously Canceled)

7. (Previously Canceled)

8. (Previously Canceled)

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9. (Previously Canceled)

10. (Previously Canceled)

11. (Previously Amended) The thermal management socket system of Claim 1, wherein said first connectors are each comprised of a receptacle structure capable of receiving a corresponding device connector from said at least one electronic device.

12. (Previously Amended) The thermal management socket system of Claim 1, wherein said first connectors are each comprised of a raised structure capable of electrically coupling with said at least one electronic device utilizing a ball grid array or a land grid array.

13. (Original) The thermal management socket system of Claim 1, wherein said thermal management unit is comprised of a base portion containing said first connectors and said second connectors, and a cap member removably connectable to said base portion for defining said chamber.

14. (Canceled)

15. (Canceled)

16. (Currently Amended) The method of utilizing a thermal management unit of Claim 23 ~~Claim 15~~, including the step of sealing said thermal management unit about said at least one electronic device.

17. (Currently Amended) The method of utilizing a thermal management unit of Claim 23, ~~including Claim 16, wherein said step of sealing said thermal management unit comprises~~ attaching a cap member in a sealed manner to a base portion of said thermal management unit.

18. (Canceled)

19. (Canceled)

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20. (Canceled)

21. (Canceled)

22. (Canceled)

23. (Currently Amended) A method of assembling a thermal management system for thermally managing at least one electronic device, said method comprising the steps of:

providing a board including at least one socket permanently attached to said board;

providing a thermal management unit including a chamber, a plurality of first connectors within said chamber, and a plurality of second connectors extending out from said thermal management unit, wherein said second connectors are electrically coupled to said first connectors and wherein said thermal management unit is to directly apply liquid coolant to said at least one electronic device within said chamber;

positioning at least one electronic device within said chamber of said thermal management unit and electrically coupling said at least one electronic device to said plurality of first connectors; and

electrically and detachably coupling said second connectors to said at least one socket.

24. (Previously Added) The method of assembling a thermal management system of Claim 23, including the step of fluidly connecting said thermal management unit to a liquid thermal management system.

25. (Currently Amended) A thermal management apparatus for thermally managing at least one electronic device, comprising a thermal management unit to receive ~~capable of receiving~~ at least one electronic device, wherein said thermal management unit is to directly apply liquid coolant to said at least one electronic device, said thermal management unit including a plurality of first connectors, and a plurality of second connectors electrically coupled to said first connectors and extending out from said thermal management unit, wherein said second connectors are electrically and removably coupled to a socket on a board.

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26. (Previously Added) The thermal management apparatus of Claim 25, including a liquid thermal management system coupled to said thermal management unit.

27. (Previously Added) The thermal management apparatus of Claim 26, wherein said liquid thermal management system is comprised of spray cooling.

28. (Previously Added) The thermal management apparatus of Claim 26, wherein said liquid thermal management system is comprised of liquid immersion.